

# MOS FET WITH SCHOTTKY BARRIER DIODE $\mu PA507TE$

# P-CHANNEL MOS FET WITH SCHOTTKY BARRIER DIODE FOR SWITCHING

### DESCRIPTION

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The  $\mu$  PA507TE is a switching device, which can be driven directly by a 1.8 V power source.

This device incorporates a MOS FET, which features a low on-state resistance and excellent switching characteristics and a low forward voltage Schottky barrier diode, and is suitable for applications such as DC/DC converter of portable machine and so on.

# **FEATURES**

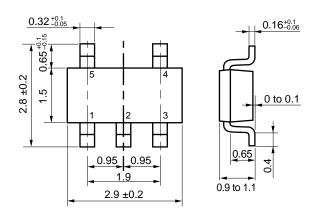
- 1.8 V drive available (MOS FET)
- Low on-state resistance (MOS FET)  $R_{DS(on)1} = 68 \text{ m}\Omega \text{ TYP}. (V_{GS} = -4.5 \text{ V}, \text{ ID} = -1.0 \text{ A})$   $R_{DS(on)2} = 84 \text{ m}\Omega \text{ TYP}. (V_{GS} = -2.5 \text{ V}, \text{ ID} = -1.0 \text{ A})$  $R_{DS(on)3} = 109 \text{ m}\Omega \text{ TYP}. (V_{GS} = -1.8 \text{ V}, \text{ ID} = -1.0 \text{ A})$
- Low forward voltage (Schottky barrier diode) VF = 0.35 V TYP. (IF = 1.0 A)

### **ORDERING INFORMATION**

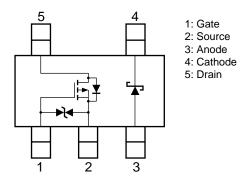
PART NUMBER	PACKAGE
$\mu$ PA507TE	SC-95_5p (Mini Mold Thin Type)

Marking: ZA

# PACKAGE DRAWING (Unit: mm)



# ★ PIN CONNECTION (Top View)



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

# Caution This product is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

VESD  $\pm$  100 V TYP. (C = 200 pF, R = 0  $\Omega$ , Single pulse)

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# MOS FET ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	-20	V
Gate to Source Voltage (VDS = 0 V)	Vgss	<b>∓8</b>	V
Drain Current (DC)	D(DC)	<b>∓2</b>	А
Drain Current (pulse) <sup>Note1</sup>	D(pulse)	<b>∓8</b>	А
Total Power Dissipation Note2	Рт	0.57	W
Channel Temperature	Tch	150	°C

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** Mounted on FR-4 board of 2500 mm<sup>2</sup> x 1.6 mm, t  $\leq$  5 sec.

# SCHOTTKY BARRIER DIODE ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Repetitive Peak Reverse Voltage	VRRM	30	V
Average Forward Current Note3	F(AV)	1	А
Surge Current Note4	IFSM	10	А
Junction Temperature	Tj	+125	°C
Storage Temperature	Tstg	–55 to +125	°C

**Notes 3.** Mounted on FR-4 board of 2500 mm<sup>2</sup> x 1.6 mm, t  $\leq$  5 sec

4. 50 Hz sine wave, 1 cycle

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V			-1	μA
Gate Leakage Current	lgss	$V_{GS}$ = $\mp$ 8 V, $V_{DS}$ = 0 V			∓10	μA
Gate Cut-off Voltage	V <sub>GS(off)</sub>	$V_{DS}$ = -10 V, I <sub>D</sub> = -1.0 mA	-0.45	-0.75	-1.50	V
Forward Transfer Admittance Note	y <sub>fs</sub>	Vds = -10 V, Id = -1.0 A	2.0	4.3		S
Drain to Source On-state Resistance Note	RDS(on)1	$V_{GS}$ = -4.5 V, $I_D$ = -1.0 A		68	85	mΩ
	RDS(on)2	$V_{GS}$ = -2.5 V, I <sub>D</sub> = -1.0 A		84	120	mΩ
	RDS(on)3	$V_{GS}$ = -1.8 V, I <sub>D</sub> = -1.0 A		109	180	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = -10 V		380		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		85		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		45		pF
Turn-on Delay Time	td(on)	$V_{DD} = -10 \text{ V}, \text{ I}_{D} = -1.0 \text{ A}$		10		ns
Rise Time	tr	V <sub>GS</sub> = -4.0 V		5		ns
Turn-off Delay Time	td(off)	R <sub>G</sub> = 10 Ω		47		ns
Fall Time	tr			28		ns
Total Gate Charge	QG	V <sub>DD</sub> = -16 V		4.7		nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = -4.0 V		0.9		nC
Gate to Drain Charge	Qgd	ID = -2.0 A		1.5		nC
Body Diode Forward Voltage Note	VF(S-D)	IF = 2.0 A, VGS = 0 V		0.84		V

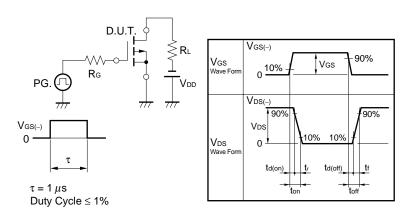
MOS FET	ELECTRICAL	CHARACTERISTICS (	$(T_A = 25^{\circ}C)$
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**Note** Pulsed: PW  $\leq$  350  $\mu$ s, Duty Cycle  $\leq$  2%

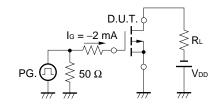
# SCHOTTKY BARRIER DIODE ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Forward Voltage	VF	I⊧ = 1.0 A		0.35	0.38	V
Reverse Current	IR	V <sub>R</sub> = 10 V			200	μA
Terminal Capacitance	Ст	f = 1.0 MHz, V <sub>R</sub> = 10 V		36		pF

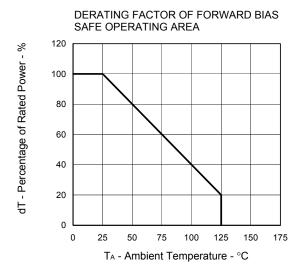
#### **TEST CIRCUIT 1 SWITCHING TIME**

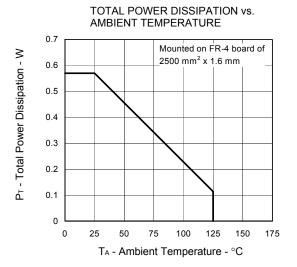


#### **TEST CIRCUIT 2 GATE CHARGE**

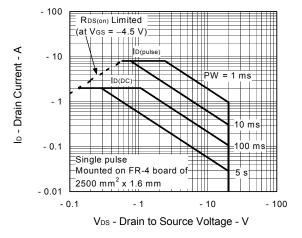


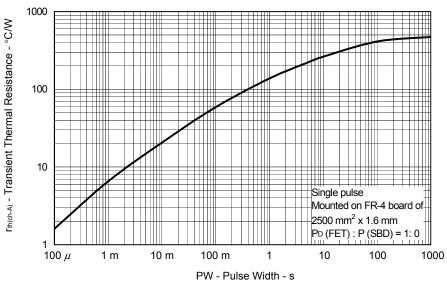
## MOS FET TYPICAL CHARACTERISTICS (TA = 25°C)



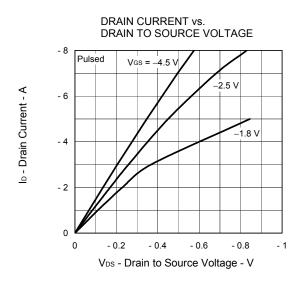


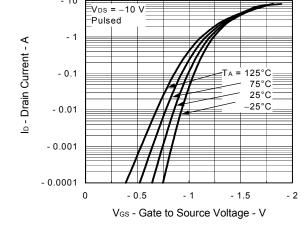
FORWARD BIAS SAFE OPERATING AREA





TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

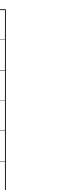




- 10

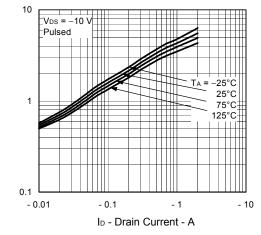
FORWARD TRANSFER CHARACTERISTICS

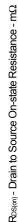
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE - 1  $V_{DS} = -10 V$ V<sub>GS(off)</sub> - Gate Cut-off Voltage - V ID = -1.0 mA - 0.9 - 0.8 - 0.7 - 0.6 - 0.5 - 0.4 - 50 0 50 100 150 Tch - Channel Temperature - °C



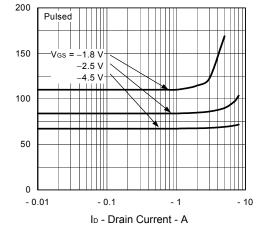
| y<sub>fs</sub> | - Forward Transfer Admittance - S

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

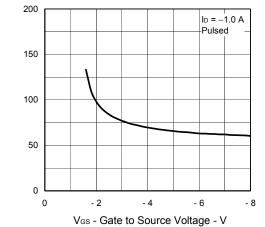




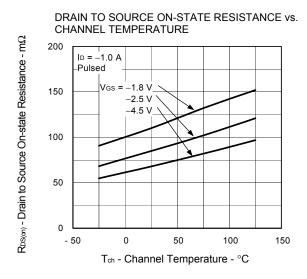
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



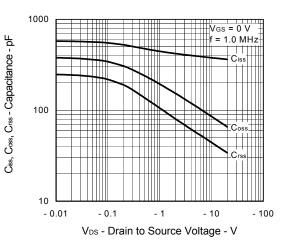
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



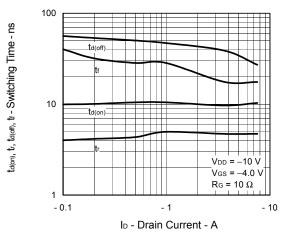
 $R_{DS(cn)}$  - Drain to Source On-state Resistance -  $m\Omega$ 

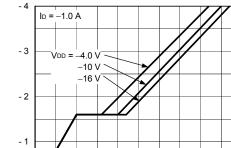


CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



SWITCHING CHARACTERISTICS





2

QG - Gate Change - nC

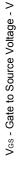
1

3

4

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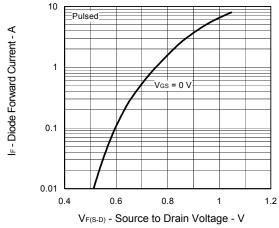
DYNAMIC INPUT CHARACTERISTICS



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SOURCE TO DRAIN DIODE FORWARD VOLTAGE

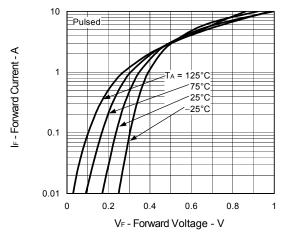


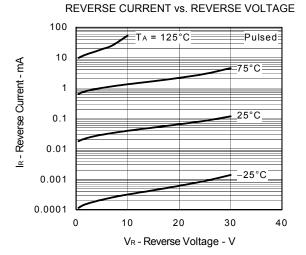
Data Sheet G16626EJ1V1DS

# SCHOTTKY BARRIER DIODE TYPICAL CHARACTERISTICS (TA = 25°C)

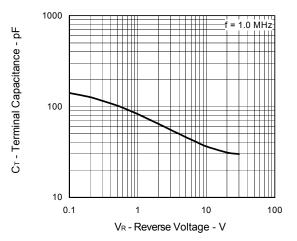
FORWARD CURRENT vs. FORWARD VOLTAGE

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TERMINAL CAPACITANCE vs. REVERSE VOLTAGE



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